

Allwinner R16 Datasheet

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Revision History

Revision	Date	Description	Version
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1

OVERVIEW

The Allwinner R16 is designed to provide a scalability, low-power capabilities, high performance application processor solution for Internet-of-Things(IoT) applications, which outperforms competitors in the terms of its system performance, great flexibility and energy-efficiency. The processor perfectly supports various applications of mainstream operating systems such as Android, Linux, etc.

R16 packs four ARM CortexTM-A7 CPU cores and Mali400MP2 graphics architecture to support display and gaming effects. Video Engine is included to provide full motion playback of up to 1080p high-definition video encoding/ decoding and supports MPEG 1/2/4, WMV9/VC1, H.263, H.264, VP8 and JPEG/MJPEG video decoding standards with dedicated hardware. The integration of display subsystem enables high resolution and high color display. Also the CMOS Sensor Interface(CSI) allows for taking photos, video input and streaming video.

The processor has optimized external memory interfaces to SDRAM, Nand Flash and SD/MMC. The SDRAM port can be configured to support DDR3 and DDR3L. In addition, to reduce total system cost and deliver better architecture scalability, R16 comes with many extensive connectivity and interfaces, including eight groups of GPIOs, six UARTs, two SPIs, four TWIs, 4-lane MIPI DSI, LVDS LCD controller, USB OTG/HOST, I2S/PCM, and a lot more.

Allwinner also designed R16 to be extremely power-efficient to realize massive ubiquitous deployment. It achieves lower power consumption with a balanced combination of several features: the exceedingly power efficient Cortex -A7 CPU cores, the advanced fabrication process, the battery-saving DVFS technology support, and the low power design architectures, etc.



2 FEATURES

2.1. CPU Architecture

The R16 platform is based on quad-core Cortex[™]-A7 CPU architecture.

- ARMv7 ISA standard instruction set plus Thumb-2 and Jazeller RCT
- NEON with SIMD and VFPv4 support
- Support hardware virtualization
- Support LPAE
- Support 4GB address space
- Support 256KB L1 cache and shared 512KB L2 cache
- Support DVFS with independent power domain

2.2. **GPU**

- Mali400MP2 GPU
- Support OpenGL ES 2.0 / OpenVG 1.1 standard





2.3. Memory Subsystem

This section consists of:

- Boot ROM
- SDRAM
- NAND Flash
- SD/MMC interface

Boot ROM

- Support system boot from Raw NAND, eMMC NAND, SPI NOR Flash, and SD/TF card
- Support system code download through USB OTG

SDRAM

- Support 2GB address space
- Support 16-bit bus width
- Compatible with JEDEC standard DDR3 /DDR3L SDRAM
- Support Memory Dynamic Frequency Scale
- Support two ranks
- Support 16 address signal lines and 3 bank signal lines

NAND Flash

- Comply to ONFI 2.3 and Toggle 1.0
- Support 64-bit ECC per 512 bytes or 1024 bytes
- Support 8-bit Raw NAND flash controller sharing pin with eMMC
- Support 2 CE and 2 RB signals
- Support SLC/MLC/TLC NAND and EF-NAND

SD/eMMC Interface

- Comply to eMMC standard specification V4.41, SD physical layer specification V2.0, SDIO card specification V2.0
- Support 4/8-bit bus width
- Support HS/DS bus mode
- Support 3 SD/eMMC controllers
- Support SDIO interrupt detection
- Support CRC generation and error detection
- Support block size from 1 to 65535 bytes



2.4. System Peripheral

This section includes:

- Timer
- High Speed Timer
- RTC
- GIC
- DMA
- CCU
- PWM

Timer

- Support two timers: clock source can be switched over 24MHz and 32768Hz
- Support two 33-bit AVS counters
- Support one 64-bit system counter from 24MHz
- Support a watchdog to generate reset signal or interrupts

High Speed Timer

- Clock source is fixed to AHB, and the pre-scale ranges from 1 to 16
- Support a 56-bit counter

RTC

- Support full clock features: second/minute/hour/day/month/year
- Support a 32768Hz clock fanout

GIC

- Support 16 SGIs, 16 PPIs and 128 SPIs
- Support ARM architecture security extensions
- Support ARM architecture virtualization extensions
- Support single processor and multiple processors environment



DMA

- 8-channel DMA
- Support data width of 8/16/32 bits
- Support linear and IO address modes
- Support data transfer types with memory-to-memory, memory-to-peripheral, peripheral-to-memory

CCU

- 11 PLLs
- Support a 24MHz oscillator, a 32768Hz oscillator and an on-chip RC oscillator
- Support clock gating control for individual components
- Clock generation, clock division, clock output

PWM

- Support two PWM outputs
- Support cycle mode and pulse mode
- Support prescale from 1 to 16



Crypto Engine

- Support Symmetrical Algorithm: AES, DES, 3DES
- Support Hash Algorithm:SHA-1, MD5
- Support 160-bits hardware PRNG with 192-bits seed
- Support ECB,CBC,CTR modes for DES/3DES
- Support ECB,CBC,CTR,CTS modes for AES
- Support 128-bits, 192-bits and 256-bits key size for AES
- 32-words RX FIFO and 32-words TX FIFO for high speed application
- CPU mode and DMA mode operation



2.6. Display Subsystem

This section includes:

- Display engine
- Video output

Display Engine

- Four movable layers, each layer size up to 2048x2048 pixels
- Ultra-Scaling engine
 - -Support four-tap scale filter in both horizontal and vertical
 - -Support input size up to 1920x1920 resolution and output size up to 1280x1280 resolution
- Support multiple image input formats: mono 1/2/4/8bpp, palette 1/2/4/8bpp, 6/24/32bpp color, YUV444/420/422/411
- Support alpha blending / color key / gamma
- Support output color correction: luminance / hue / saturation, etc
- Support Saturation Enhancement and Dynnmic Range Control
- Support realtime write back function

Video Output

- Support CPU / Sync RGB / LVDS LCD interface up to 1280x800 resolution
- Support 1/2/4-lane MIPI DSI interface up to 1280x800 resolution
 - -Support MIPI DSI V1.01 and MIPI D-PHY V1.00
 - -Support command mode and video mode (non-burst mode with sync pulses, non-burst mode with sync event and burst mode)
- Support RGB666 dither function



2.7. Video Engine

Video Decoding

- Support video playback up to 1920x1080@60fps
- Support multi-format video playback, including MPEG1/2, MPEG4 SP/ASP GMC, WMV9/VC1, H.263 including Sorenson Spark, H.264 BP/MP/HP, VP8, WMV9/VC-1, JPEG/MJPEG, etc

Video Encoding

- Support H.264 HP video encoding up to 1920x1080@60fps
- JPEG baseline: picture size up to 4080x4080
- Support Alpha blending
- Support thumb generation
- Support 4x2 scaling ratio: from 1/16 to 64 arbitrary non-integer ratio





2.8. Video Input

CSI

- · Support parallel camera sensor
- Support 8-bit CCIR601/656 interface
- Support up to 5M pixel camera sensor
- Support dual outputs for display and encoding

2.9. Audio Subsystem

Audio Codec

- Support stereo audio DAC
 - -Up to 100dB SNR
 - -8KHz ~ 192KHz DAC sample rate
- Support stereo audio ADC
 - -Up to 92dB SNR
 - -8KHz ~ 48KHz ADC sample rate
- Support four analog audio inputs
 - -Two microphone differential inputs for main mic and headphone mic
 - -One differential phone input for modem
 - -One stereo line-in input for FM
- Support two analog audio outputs
 - -One stereo or differential capless headphone output
 - -One differential earpiece output
- Support Talking Standby Mode, where the application processor remains inactive during voice call application for power saving, support noise reduction
- Support Dynamic Range Controller(DRC) adjusting the DAC playback output
- Support Automatic Gain Control(AGC) adjusting the ADC recording output
- Two PCM interface connected with BB and BT





2.10 External Peripherals

This section includes:

- USB 2.0 OTG
- USB HOST
- LRADC
- Digital Audio Interface
- UART
- SPI
- Open-drain TWI
- RSBTM

USB 2.0 OTG

- Support High-Speed (HS, 480Mbps), Full-Speed (FS, 12Mbps), and Low-Speed (LS, 1.5Mbps) in Host mode
- Support High-Speed (HS, 480Mbps) and Full-Speed (FS, 12Mbps) in Device mode
- Support up to five configurable endpoints for bulk, isochronous, control and interrupt
- Support the embeded DMA

USB Host

- EHCI/OHCI-compliant host
- USB2.0 PHY and HSIC
- Support High-Speed(HS,480Mbps), Full-Speed(FS,12Mbps), and Low-Speed(LS,1.5Mbps)Device
- An internal DMA Controller for data transfer with memory

KEYADC

- 6-bit resolution
- Support hold key and continuous key
- Support single key,normal key and continuous key

Digital Audio Interface

- Two I2S/PCM compliant digital audio interfaces for modem and bluetooth
- I2S or PCM configured by software
- Support 3 I2S Data formats:Standard I2S,Left Justified and Right Justified
- I2S supports 2 channels output and 2 channels input
- PCM supports linear sample(8-bit or 16-bit), 8-bit u-law and A-law companded sample
- Sample rate from 8KHz to 192KHz
- Support 16,20,24bits audio data resolutions
- One 128x24-bits FIFO for data transmit, one 64x24-bits FIFO for data receive



UART

- Support six UART controllers
- FIFO size up to 64 bytes
- Support speed up to 3MHz
- Compliant with industry-standard 16550 UARTs
- Support Infrared Data Association(IrDA)1.0 SIR

SPI

- Two SPI controllers
- Full-duplex synchronous serial interface
- Master/Slave configurable
- Polarity and phase of the Chip Select and SPI Clock are configurable
- Two 64-bytes FIFO for SPI-TX and SPI-RX operation
- DMA-based or interrupt-based operation

TWI

- Up to four TWI(Two Wire Interface) controllers
- Support one dedicated TWI controller for CSI
- Support speed up to 400Kbps
- Master/Slave configurable
- Allows 10-bits addressing transactions

RSB[™] (Reduced Serial Bus)

- Support transfer speed up to 20MHz
- Support Push-Pull bus
- Support Host mode
- Support multiple devices
- Programmable output delay of CD signal
- Parity check for address and data transmission







2.11. Power Management

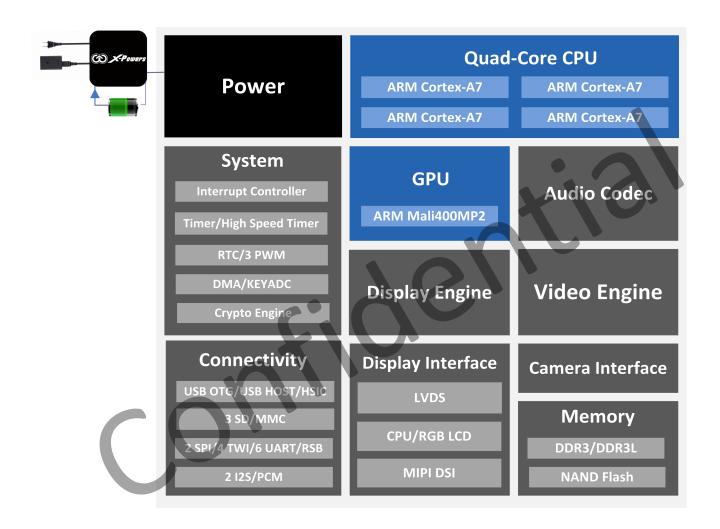
- Support DVFS for CPU frequency and voltage adjustment
- Support super standby mode for energy efficiency
- Support talking standby mode for energy efficiency during voice call application

2.12. Package

• TFBGA 282 balls,0.8mm ball pitch, 14 x 14 x 1.4-mm



3 BLOCK DIAGRAM



R16 Block Diagram



4

PIN DESCRIPTION

4.1. PIN CHARACTERISTICS

Following table describes the R16 pin characteristics from seven aspects: **BALL#**, **Pin Name**, **Default Function**¹, **Type**², **Reset State**³, **Default Pull Up/Down**⁴, **and Buffer Strength**⁵.

BALL#	Pin Name	Default Function	Туре	Reset State	Default Pull Up/Down	Buffer Strength (mA)
SDRAM						
M1	DQ0	DRAM	I/O	Z	-	-
M2	DQ1	DRAM	I/O	Z	-	-
L1	DQ2	DRAM	I/O	Z	-	-
L2	DQ3	DRAM	I/O	Z	-	-
J1	DQ4	DRAM	1/0	Z	-	-
J2	DQ5	DRAM	I/O	Z	-	-
H1	DQ6	DRAM	I/O	Z	-	-
H2	DQ7	DRAM	1/0	Z	-	-
U3	DQ8	DRAM	I/O	Z	-	-
U1	DQ9	DRAM	I/O	Z	-	-
U2	DQ10	DRAM	I/O	Z	-	-
T2	DQ11	DRAM	I/O	Z	-	-
R2	DQ12	DRAM	I/O	Z	-	-
P1	DQ13	DRAM	I/O	Z	-	-
P2	DQ14	DRAM	I/O	Z	-	-
N1	DQ15	DRAM	I/O	Z	-	-
M4	DVREF	DRAM	Р	-	-	-
R1	DQS1	DRAM	I/O	Z	-	-
T1	DQS1B	DRAM	I/O	Z	-	-
T3	DQM1	DRAM	0	Z	-	-
K2	DQS0	DRAM	I/O	Z	-	-
K1	DQS0B	DRAM	I/O	Z	-	-
N2	DQM0	DRAM	0	Z	-	-

Note:

- 1 **Default function** defines the default function of each pin, especially for pins with multiplexing functions;
- 2 There are five *pin types* here: O for output, I for input, I/O for input/output, A for analog,OD for Open-Drain, P for power and G for ground;
- 3 Reset state defines the state of the terminal at reset: Z for high-impedance,F for Multiplexing Function Pin;
- 4 **Default Pull up/down** defines the presence of an internal pull up or pull down resistor. Unless otherwise specified, the pin is default to be floating, and can be configured as pull up or pull down;
- 5 **Buffer strength** defines the driver strength of the associated output buffer. It is tested in the condition that VCC= 3.0V, strength=MAX;



BALL#	Pin Name	Default	Type	Reset State	Default Pull	Buffer
DALLII	1 III Italiio	Function	1 9 00	reset state	Up/Down	Strength (mA)
G2	DCKB	DRAM	0	Z	_	_
G1	DCK	DRAM	0	Z	_	_
J4	DCKE	DRAM	0	Z	_	<u>-</u>
N7	DCKE1	DRAM	0	Z	_	_
E4	DA0	DRAM	0	Z	_	-
D1	DA1	DRAM	0	Z	_	-
F2	DA1	DRAM	0	Z	-	-
H3	DA3	DRAM	0	Z	_	_
D2	DA3	DRAM	0	Z	-	-
F1	DA4	DRAM	0	Z	-	<u>-</u>
						- -
A1	DA6	DRAM	0	Z	-	-
G4	DA7	DRAM	0	Z	-	-
B1	DA8	DRAM	0	Z	-	-
F4	DA9	DRAM	0	Z	-	-
E2	DA10	DRAM	0	Z	-	-
C2	DA11	DRAM	0	Z	-	-
E1	DA12	DRAM	0	Z		-
F3	DA13	DRAM	0	Z		-
C1	DA14	DRAM	0	Z	-	-
E3	DA15	DRAM	0	Z Z Z	-	-
J3	DBA0	DRAM	0	Z	-	-
K4	DBA1	DRAM	Q	Z	-	-
H4	DBA2	DRAM	0	Z	-	-
K3	DWE	DRAM	0	Z	-	-
M3	DCAS	DRAM	0	Z	-	-
L4	DRAS	DRAM	0	Z	-	-
N3	DCS	DRAM	0	Z	-	_
N5	DCS1	DRAM	0	Z	-	-
L3	DODT	DRAM	0	Z	_	_
L7	DODT1	DRAM	0	Z	_	_
R3	DZQ	DRAM	A	Z	_	_
G3	DRST	DRAM	0	Z	_	_
P3	VDD-DLL	POWER	P	-	_	_
H5,J5,K5,L5,	VDB BLE	TOWER				
H6,J6	VCC-DRAM	POWER	Р	-	-	-
GPIO B						
G17	PB0	GPIO	I/O	Z	NO PULL	20
G16	PB1	GPIO	I/O	Z	NO PULL	20
F17	PB2	GPIO	I/O	Z	NO PULL	20
F16	PB3	GPIO	1/0	Z	NO PULL	20
G14	PB4	GPIO	1/0	Z	NO PULL	20
G15	PB5	GPIO	I/O	Z	NO PULL	20
F14	PB6	GPIO	I/O	Z	NO PULL	20
F15	PB7	GPIO	I/O	Z	NO PULL	20
GPIO C				_		
D12	PC0	GPIO	I/O	Z	NO PULL	20
C12	PC1	GPIO	I/O	Z	NO PULL	20
C11	PC2	GPIO	I/O	Z	NO PULL	20
D11	PC3	GPIO	I/O	Z	PULL UP	20
B11	PC4	GPIO	I/O	Z	PULL UP	20



		Default			Default Pull	Buffer
BALL#	Pin Name	Function	Type	Reset State	Up/Down	Strength (mA)
C10	PC5	GPIO	I/O	Z	NO PULL	20
D10	PC6	GPIO	I/O	Z	PULL UP	20
A12	PC7	GPIO	I/O	Z	NO PULL	20
A11	PC8	GPIO	I/O	Z	NO PULL	20
B10	PC9	GPIO	I/O	Z	NO PULL	20
A10	PC10	GPIO	I/O	Z	NO PULL	20
B9	PC11	GPIO	I/O	Z	NO PULL	20
A9	PC12	GPIO	I/O	Z	NO PULL	20
B8	PC13	GPIO	I/O	Z	NO PULL	20
A8	PC14	GPIO	I/O	Z	NO PULL	20
B7	PC15	GPIO	I/O	Z	NO PULL	20
A7	PC16	GPIO	I/O	Z	NO PULL	20
GPIO D	1 0 10	0110	1/0		NOTOLL	20
R12	PD2	GPIO	I/O	Z	NO PULL	20
P12	PD3	GPIO	I/O	Z	NO PULL	20
R11	PD4	GPIO	I/O	Z	NO PULL	20
P11	PD5	GPIO	I/O	Z	NO PULL	20
R10	PD6	GPIO	I/O	Z	NO PULL	20
P10	PD7	GPIO	I/O	Z	NO PULL	20
R9	PD10	GPIO	I/O	7	NO PULL	20
P9	PD11	GPIO	1/0	Z Z Z	NO PULL	20
R8	PD12	GPIO	1/0	7	NO PULL	20
P8	PD13	GPIO	1/0	Z	NO PULL	20
R7	PD14	GPIO	1/0	Z	NO PULL	20
P7	PD15	GPIO	1/0	Z	NO PULL	20
U11	PD18	GPIO	1/0	Z	NO PULL	20
T11	PD19	GPIO	I/O	Z	NO PULL	20
U10	PD19	GPIO	1/0	Z	NO PULL	20
T10	PD21	GPIO	1/0	Z	NO PULL	20
U9	PD21	GPIO	I/O	Z	NO PULL	20
		_		Z		
Т9	PD23	GPIO	I/O		NO PULL	20
U8	PD24	GPIO	I/O	Z	NO PULL	20
T8	PD25	GPIO	I/O	Z	NO PULL	20
U7	PD26	GPIO	I/O	Z	NO PULL	20
T7	PD27	GPIO	I/O	Z	NO PULL	20
M11,N11	VCC-PD	POWER	Р	-	-	-
GPIO E	DE0	0010	1/0		NO DUIL	
C5	PE0	GPIO	I/O	Z	NO PULL	20
D5	PE1	GPIO	I/O	Z	NO PULL	20
C6	PE2	GPIO	I/O	Z	NO PULL	20
D6	PE3	GPIO	I/O	Z	NO PULL	20
A6	PE4	GPIO	I/O	Z	NO PULL	20
B6	PE5	GPIO	I/O	Z	NO PULL	20
A5	PE6	GPIO	I/O	Z	NO PULL	20
B5	PE7	GPIO	I/O	Z	NO PULL	20
A4	PE8	GPIO	I/O	Z	NO PULL	20
B4	PE9	GPIO	I/O	Z	NO PULL	20
A3	PE10	GPIO	I/O	Z	NO PULL	20
B3	PE11	GPIO	I/O	Z	NO PULL	20
A2	PE12	GPIO	I/O	Z	NO PULL	20



BALL#	Pin Name	Default	Type	Reset State	Default Pull	Buffer
DALLII	i iii ivaiiio	Function	1 9 60	reset state	Up/Down	Strength (mA)
B2	PE13	GPIO	I/O	Z	NO PULL	20
C3	PE14	GPIO	I/O	Z	NO PULL	20
D3	PE15	GPIO	I/O	Z	NO PULL	20
C4	PE16	GPIO	I/O	Z	NO PULL	20
D4	PE17	GPIO	I/O	Z	NO PULL	20
GPIO F			ı		1	
D9	PF0	GPIO	I/O	F	NO PULL	20
C9	PF1	GPIO	I/O	F	NO PULL	20
D8	PF2	GPIO	I/O	Z	NO PULL	20
C8	PF3	GPIO	I/O	F	NO PULL	20
D7	PF4	GPIO	I/O	Z	NO PULL	20
C7	PF5	GPIO	I/O	F	NO PULL	20
GPIO G		00	0	·		
A15	PG0	GPIO	I/O	Z	NO PULL	20
B15	PG1	GPIO	I/O	Z	NO PULL	20
A14	PG2	GPIO	I/O	Z	NO PULL	20
B14	PG3	GPIO	I/O	Z	NO PULL	20
A13	PG4	GPIO	I/O	Z	NO PULL	20
B13	PG5	GPIO	I/O		NO PULL	20
A17	PG6	GPIO	I/O	Z Z Z Z	NO PULL	20
B17	PG7	GPIO	1/0	7	NO PULL	20
A16	PG9	GPIO	I/O	7	NO PULL	20
B16	PG8	GPIO	1/0		NO PULL	20
C17	PG10	GPIO	1/0	Z	NO PULL	20
C16				Z		20
	PG11	GPIO CPIO	1/0		NO PULL	
C15	PG12	GPIO	1/0	Z	NO PULL	20
C14	PG13	GPIO	1/0	Z	NO PULL	20
GPIO H	DUID	ODIO	1/0	7	NO DUIL	00
D17	PH0	GPIO	I/O	Z	NO PULL	20
D16	PH1	GPIO	I/O	Z	NO PULL	20
D15	PH2	GPIO	I/O	Z	NO PULL	20
D14	PH3	GPIO	I/O	Z	NO PULL	20
D13	PH4	GPIO	I/O	Z	NO PULL	20
C13	PH5	GPIO	I/O	Z	NO PULL	20
E17	PH6	GPIO	I/O	Z	NO PULL	20
E16	PH7	GPIO	I/O	Z	NO PULL	20
E15	PH8	GPIO	I/O	Z	NO PULL	20
E14	PH9	GPIO	I/O	Z	NO PULL	20
GPIO L						
P16	PL0	GPIO	I/O	Z	PULL UP	20
P15	PL1	GPIO	I/O	Z	PULL UP	20
U14	PL2	GPIO	I/O	Z	NO PULL	20
T14	PL3	GPIO	I/O	Z	NO PULL	20
R14	PL4	GPIO	I/O	Z	NO PULL	20
P14	PL5	GPIO	I/O	Z	NO PULL	20
U13	PL6	GPIO	I/O	Z	NO PULL	20
T13	PL7	GPIO	I/O	Z	NO PULL	20
R13	PL8	GPIO	I/O	Z	NO PULL	20
P13	PL9	GPIO	I/O	Z	NO PULL	20
U12	PL10	GPIO	I/O	Z	NO PULL	20
T12	PL11	GPIO	I/O	Z	NO PULL	20



DA!!#	Dia Norma	Default	T.	Decet 04-4	Default Pull	Buffer
BALL#	Pin Name	Function	Type	Reset State	Up/Down	Strength (mA)
SYSTEM CON						
N14	NMI	-	l	Z	NO PULL	-
P17	RESET	-	l	Z	NO PULL	-
USB						
T16	USB-DM0	-	Α	-	-	-
T17	USB-DP0	-	Α	-	-	-
U16	USB-DM1	-	Α	-	-	-
U17	USB-DP1	-	Α	-	-	-
L12	VCC-USB	-	Р	-	-	-
HSIC						
N12	VCC-HSIC	-	Р	_	_	-
T15	HSIC-STR	-	Α	-	-	-
U15	HSIC-DAT	-	А	_	_	-
AUDIO CODEO			, , ,			
M16	MIC1N		Α	_	_	
M17	MIC1P	<u> </u>	A	-		
N16	MIC2N		A	_		7 -
N17	MIC2P		A			_
J15	LINEINR		A			<u>-</u>
H15	LINEINL	-	A	W N		-
K16	VRA1	<u> </u>	A		-	-
K17	VRA2	<u> </u>	A		_	-
L16	AVCC	-	P	-		
L17	VRP			-	-	-
N15	PHONEOUTN		A	-	-	-
M15			A		-	-
K15	PHONEOUTP		A	-	-	-
L15	PHONEINN	-	A	-	-	-
	PHONEINP	-	A	-	-	-
J14	HBIAS			-	-	-
K14	MBIAS	-	A	-	-	-
H13	AGND	-	G	-	-	-
J16	HPOUTR	-	A	-	-	-
J17	HPOUTL	-	A	-	-	-
H14	HPCOM	-	Α	-	-	-
H16	HPCOMFB	-	A	-	-	-
H17	HPVCCBP	-	P	-	-	-
K13	HPVCCIN	-	Р	-	-	-
LRADC			_			
L14	LRADC0	-	Α	-	-	-
DSI	50.					
R4	DSI-D0N	-	Α	-	-	-
P4	DSI-D0P	-	Α	-	-	-
R5	DSI-D1N	-	Α	-	-	-
P5	DSI-D1P	-	Α	-	-	-
U6	DSI-D2N	-	Α	-	-	-
T6	DSI-D2P	-	Α	-	-	-
R6	DSI-D3N	-	Α	-	-	-
P6	DSI-D3P	-	Α	-	-	-
U5	DSI-CKN	-	Α	-	-	-
T5	DSI-CKP	-	Α	-	-	-
N6	VCC-DSI	-	Р	-	-	-



BALL#	Pin Name	Default Function	Туре	Reset State	Default Pull Up/Down	Buffer Strength (mA)
CLOCK					_	
R17	X32KIN	-	Α	_	_	_
R16	X32KOUT	-	Α	-	-	_
R15	X32KFOUT	-	Α	-	-	-
M13	RTCVIO	-	Р	-	-	-
M12	VCC-RTC	-	Р	-	-	_
U4	X24MIN	-	Α	-	-	-
T4	X24MOUT	-	Α	-	-	-
M5	VCC-PLL	-	Р	-	-	-
POWER						
M8	VCC-EFUSE	-	Р	-	-	-
M14	VDD-CPUS	-	Р	-	-	-
E5,E6,E7,F5,F6, F7,G5,G6	VDD-CPU	-	Р	-	-	-
E8,E9,E10,K6, L6,M6,M7,N8 N9,N10	VDD-SYS	-	Р	-	3	
E11,E12,F11 F12,G12	VCC-IO	-	Р		<u></u>	-
N4,F8,F9,F10, G7,G8,G9,G10, G11,H7,H8, H9,H10,H11, H12,J7,J8,J9, J10,J11,J12 K7,K8,K9,K10, K11,K12, L8,L9,L10, L11,M9,M10	GND	-	G	-	-	-



4.2. GPIO MULTIPLEXING FUNCTIONS

Following table provides a description of the GPIO multiplexing functions of R16.

David	Default	10 T	Default	Default Pull	Multiplexed	Multiplexed	Multiplexed
Port	Function	IO Type	IO State	Up/Down	Function 2	Function 3	Function 4
PB0	GPIO	I/O	DIS	Z	UART2-TX	UART0-TX	PB-EINT0
PB1	GPIO	I/O	DIS	Z	UART2-RX	UART0-RX	PB-EINT1
PB2	GPIO	I/O	DIS	Z	UART2-RTS	-	PB-EINT2
PB3	GPIO	I/O	DIS	Z	UART2-CTS	-	PB-EINT3
PB4	GPIO	I/O	DIS	Z	PCM0-SYNC	AIF2-SYNC	PB-EINT4
PB5	GPIO	I/O	DIS	Z	PCM0-BCLK	AIF2-BCLK	PB-EINT5
PB6	GPIO	I/O	DIS	Z	PCM0-DOUT	AIF2-DOUT	PB-EINT6
PB7	GPIO	I/O	DIS	Z	PCM0-DIN	AIF2-DIN	PB-EINT7
PC0	GPIO	I/O	DIS	Z	NAND-WE	SPI0-MOSI	-
PC1	GPIO	I/O	DIS	Z	NAND-ALE	SPI0-MISO	-/-
PC2	GPIO	I/O	DIS	Z	NAND-CLE	SPI0-CLK	
PC3	GPIO	I/O	DIS	Pull-up	NAND-CE1	SPI0-CS	_
PC4	GPIO	I/O	DIS	Pull-up	NAND-CE0		-
PC5	GPIO	I/O	DIS	Z	NAND-RE	SDC2-CLK	-
PC6	GPIO	I/O	DIS	Pull-up	NAND-RB0	SDC2-CMD	_
PC7	GPIO	I/O	DIS	Pull-up	NAND-RB1	-	-
PC8	GPIO	I/O	DIS	Z	NAND-DQ0	SDC2-D0	-
PC9	GPIO	I/O	DIS		NAND-DQ1	SDC2-D1	-
PC10	GPIO	I/O	DIS	Z Z Z	NAND-DQ2	SDC2-D2	_
PC11	GPIO	I/O	DIS	Z	NAND-DQ3	SDC2-D3	-
PC12	GPIO	I/O	DIS		NAND-DQ4	SDC2-D4	-
PC13	GPIO	I/O	DIS	Z Z	NAND-DQ5	SDC2-D5	-
PC14	GPIO	1/0	DIS	Z	NAND-DQ6	SDC2-D6	-
PC15	GPIO	I/O	DIS	Z	NAND-DQ7	SDC2-D7	-
PC16	GPIO	I/O	DIS	Z	NAND-DQS	SDC2-RST	-
PD2	GPIO	I/O	DIS	Z	LCD-D2	SDC1-CLK	-
PD3	GPIO	I/O	DIS	Z	LCD-D3	SDC1-CMD	-
PD4	GPIO	I/O	DIS	Z	LCD-D4	SDC1-D0	-
PD5	GPIO	I/O	DIS	Z	LCD-D5	SDC1-D1	-
PD6	GPIO	I/O	DIS	Z	LCD-D6	SDC1-D2	-
PD7	GPIO	I/O	DIS	Z	LCD-D7	SDC1-D3	-
PD10	GPIO	I/O	DIS	Z	LCD-D10	UART1-TX	-
PD11	GPIO	I/O	DIS	Z	LCD-D11	UART1-RX	-
PD12	GPIO	I/O	DIS	Z	LCD-D12	UART1-RTS	-
PD13	GPIO	I/O	DIS	Z	LCD-D13	UART1-CTS	-
PD14	GPIO	I/O	DIS	Z	LCD-D14		-
PD15	GPIO	I/O	DIS	Z	LCD-D15		-
PD18	GPIO	I/O	DIS	Z	LCD-D18	LVDS-VP0	-
PD19	GPIO	I/O	DIS	Z	LCD-D19	LVDS-VN0	-
PD20	GPIO	I/O	DIS	Z	LCD-D20	LVDS-VP1	-
PD21	GPIO	I/O	DIS	Z	LCD-D21	LVDS-VN1	-
PD22	GPIO	I/O	DIS	Z	LCD-D22	LVDS-VP2	-
PD23	GPIO	I/O	DIS	Z	LCD-D23	LVDS-VN2	-
PD24	GPIO	I/O	DIS	Z	LCD-CLK	LVDS-VPC	-
PD25	GPIO	I/O	DIS	Z	LCD-DE	LVDS-VNC	-



PD26	CDIO	1/0	DIS	7	I CD HEAVIO	LVDS VD3	
PD26 PD27	GPIO GPIO	I/O I/O	DIS	Z	LCD-HSYNC LCD-VSYNC	LVDS-VP3 LVDS-VN3	-
PD27 PE0	GPIO GPIO	I/O	DIS	Z	CSI-PCLK	LVDO-VINO	-
PE1	GPIO	I/O	DIS	Z	CSI-MCLK	-	-
PE2	GPIO	I/O	DIS	Z	CSI-HSYNC	-	-
PE3		I/O	DIS	Z	CSI-VSYNC	-	-
	GPIO			Z		-	-
PE4	GPIO	1/0	DIS	Z	CSI-D0	-	-
PE5	GPIO	1/0	DIS	Z	CSI-D1	-	-
PE6	GPIO	1/0	DIS	Z	CSI-D2	-	-
PE7	GPIO	1/0	DIS		CSI-D3	-	-
PE8	GPIO	1/0	DIS	Z	CSI-D4	-	-
PE9	GPIO	I/O	DIS	Z	CSI-D5	-	-
PE10	GPIO	I/O	DIS	Z	CSI-D6	-	-
PE11	GPIO	I/O	DIS	Z	CSI-D7	- TIA//0.001/	
PE12	GPIO	1/0	DIS	Z	CSI-SCK	TWI2-SCK	-
PE13	GPIO	I/O	DIS	Z	CSI-SDA	TWI2-SDA	-
PE14	GPIO	I/O	DIS	Z	-	-	
PE15	GPIO	I/O	DIS	Z	-	-	
PE16	GPIO	I/O	DIS	Z	-		- 7
PE17	GPIO	I/O	DIS	Z	-	7	
PF0	GPIO	I/O	JTAG	F	SDC0-D1	JTAG-MS1	-
PF1	GPIO	I/O	JTAG	F	SDC0-D0	JTAG-DI1	-
PF2	GPIO	I/O	DIS	Z	SDC0-CLK	UART0-TX	-
PF3	GPIO	I/O	JTAG	F	SDC0-CMD	JTAG-DO1	-
PF4	GPIO	I/O	DIS	Z	SDC0-D3	UART0-RX	-
PF5	GPIO	I/O	JTAG	F	SDC0-D2	JTAG-CK1	-
PG0	GPIO	I/O	DIS	Z	SDC1-CLK	-	PG-EINT0
PG1	GPIO	I/O	DIS	Z	SDC1-CMD	-	PG-EINT1
PG2	GPIO	I/O	DIS	Z	SDC1-D0	-	PG-EINT2
PG3	GPIO	I/O	DIS	Z	SDC1-D1	-	PG-EINT3
PG4	GPIO	I/O	DIS	Z	SDC1-D2	-	PG-EINT4
PG5	GPIO	1/0	DIS	Z	SDC1-D3	-	PG-EINT5
PG6	GPIO	I/O	DIS	Z	UART1-TX	-	PG-EINT6
PG7	GPIO	I/O	DIS	Z	UART1-RX	-	PG-EINT7
PG8	GPIO	I/O	DIS	Z	URAT1-RTS	-	PG-EINT8
PG9	GPIO	I/O	DIS	Z	UART1-CTS	-	PG-EINT9
PG10	GPIO	I/O	DIS	Z	PCM1-SYNC	AIF3-SYNC	PG-EINT10
PG11	GPIO	I/O	DIS	Z	PCM1-BCLK	AIF3-BCLK	PG-EINT11
PG12	GPIO	I/O	DIS	Z	PCM1-DOUT	AIF3-DOUT	PG-EINT12
PG13	GPIO	I/O	DIS	Z	PCM1-DIN	AIF3-DIN	PG-EINT13
PH0	GPIO	I/O	DIS	Z	PWM0	-	-
PH1	GPIO	I/O	DIS	Z	PWM1	-	-
PH2	GPIO	I/O	DIS	Z	TWI0-SCK	-	-
PH3	GPIO	I/O	DIS	Z	TWI0-SDA	-	-
PH4	GPIO	I/O	DIS	Z	TWI1-SCK	-	-
PH5	GPIO	I/O	DIS	Z	TWI1-SDA	-	-
PH6	GPIO	I/O	DIS	Z	SPI0-CS	UART3-TX	-
PH7	GPIO	I/O	DIS	Z	SPI0-CLK	UART3-RX	-
PH8	GPIO	I/O	DIS	Z	SPI0-MOSI	UART3-RTS	-
PH9	GPIO	I/O	DIS	Z	SPI0-MISO	UART3-CTS	-
	GPIO	I/O	DIS	Pull-up	S-RSB-SCK	S-TWI-SCK	S-PL-EINT0
PLU	GIIO						
				Pull-up	S-RSB-SDA	S-TWI-SDA	S-PL-EINT1
PL1	GPIO	I/O	DIS	Pull-up Z	S-RSB-SDA S-UART-TX	S-TWI-SDA	S-PL-EINT1 S-PL-EINT2
PL0 PL1 PL2 PL3				Pull-up Z Z	S-RSB-SDA S-UART-TX S-UART-RX	S-TWI-SDA - -	S-PL-EINT1 S-PL-EINT2 S-PL-EINT3



PL5	GPIO	I/O	DIS	Z	S-JTAG-CK	-	S-PL-EINT5
PL6	GPIO	I/O	DIS	Z	S-JTAG-DO	-	S-PL-EINT6
PL7	GPIO	I/O	DIS	Z	S-JTAG-DI	-	S-PL-EINT7
PL8	GPIO	I/O	DIS	Z	S-TWI-SCK	-	S-PL-EINT8
PL9	GPIO	I/O	DIS	Z	S-TWI-SDA	-	S-PL-EINT9
PL10	GPIO	I/O	DIS	Z	S-PWM	-	S-PL-EINT10
PL11	GPIO	I/O	DIS	Z	-	-	S-PL-EINT11

4.3. DETAILED PIN/SIGNAL DESCRIPTION

Pin/Signal	Description	Type
DRAM		
DQ[15:0]	DRAM DQ[15:0]	I/O
DVREF	DRAM Reference Input	P
DQS[1:0]	DRAM Data Strobe DQS[1:0]	1/0
DQSB[1:0]	DRAM Data Strobe DQSB[1:0]	VO
DCK	DRAM Clock	0
DCKB	DRAM CKB	0
DCKE[1:0]	DRAM Clock Enable [1:0]	0
DA[15:0]	DRAM Data Address[15:0]	0
DBA[2:0]	DRAM Bank Address[2:0]	0
DWE	DRAM Write Enable	0
DCAS	DRAM Column Address Strobe	0
DRAS	DRAM Row Address Strobe	0
DCS[1:0]	DRAM Chip Select[1:0]	0
DODT[1:0]	DRAM ODT Control [1:0]	0
DZQ	DRAM ZQ Calibration	A
DRST	DRAM Reset	0
VDD-DLL	DLL Power Supply	Р
VCC-DRAM	DRAM Power Supply	Р
GPIO		
PB[7:0]	Port B Bit[7:0]	I/O
PC[18:0]	Port C Bit[18:0]	I/O
PD[27:0]	Port D Bit[27:0]	I/O
VCC-PD	Port D Power Supply	Р
PE[17:0]	Port E Bit[17:0]	I/O
PF[5:0]	Port F Bit[5:0]	I/O
PG[13:0]	Port G Bit[13:0]	I/O
PH[9:0]	Port H Bit[9:0]	I/O
PL[11:0]	Port L Bit[11:0]	I/O
SYSTEM CONTROL		
NMI	Non-Maskable Interrupt	
RESET	Reset Signal	
INTERRUPT		
EINT	External Interrupt	1
PWM		
PWM[1:0]	PWM	0
CLOCK		
X32KIN	Clock Input of 32768Hz Crystal	Α



Pin/Signal	Description	Туре		
X32KOUT	Clock Output of 32768Hz Crystal	A		
X32KFOUT	Clock Output of LOSC (X32KFOUT can be gating)	OD		
RTCVIO	RTC Power	Р		
VCC-RTC	RTC Power Supply	Р		
X24MIN	Clock Input of 24MHz Crystal	Α		
X24MOUT	Clock Output of 24MHz Crystal	A		
VCC-PLL	PLL Power	Р		
NAND FLASH				
NAND-DQ[7:0]	NAND Flash Data Bit[7:0]	I/O		
NAND-CE[1:0]	NAND Flash Chip Select[1:0]	0		
NAND-WE	NAND Flash Write Enable	0		
NAND-ALE	NAND Flash Address Latch Enable	0		
NAND-CLE	NAND Flash Command Latch Enable	0		
NAND-RE	NAND Flash Read Enable	0		
NAND-RB	NAND Flash Ready/Busy Bit	I		
NAND-DQS	NAND Flash Data Strobe	1/0		
LCD				
LCD-D[23:0]	LCD Data Bit[23:0]	0		
LCD-CLK	LCD Clock Signal	0		
LCD-DE	LCD Data Enable	0		
LCD-HSYNC	LCD Horizontal SYNC	0		
LCD-VSYNC	LCD Vertical SYNC	0		
LVDS	LCD vertical STNC	U		
	LVDS Data Positive Signal Output[3:0]	^		
LVDS-VP[3:0]		A		
LVDS-VN[3:0]	LVDS Data Negative Signal Output[3:0] LVDS Clock Positive Output	A		
LVDS-VPC		A		
LVDS-VNC	LVDS Clock Negative Output	A		
DSI				
DSI-DN(3:0)	DSI Data Negative	A		
DSI-DP(3:0)	DSI Data Positive	Α		
DSI-CKN	DSI Clock Negative	Α		
DSI-CKP	DSI Clock Positive	Α		
VCC-DSI	DSI Power Supply	Р		
CSI				
CSI-D[7:0]	CSI0 Data Bit[7:0]	I		
CSI-PCLK	CSI Pixel Clock	I		
CSI-MCLK	CSI Master Clock	0		
CSI-SCK	CSI Clock Signal	0		
CSI-SDA	CSI Data Signal	IO		
CSI-HSYNC	CSI Horizontal SYNC	I		
CSI-VSYNC	CSI Vertical SYNC	l		
USB		I		
USB-DM[1:0]	USB DM[1:0] Signal	A		
USB-DP[1:0]	USB DP[1:0] Signal	A		
VCC-USB	USB Power Supply	P		
HSIC		· ·		
VCC-HSIC	HSIC Power Supply	Р		
HSIC-STR	USB HSIC Strobe signal	A		
HSIC-DAT	USB HSIC Data signal	A		
AUDIO CODEC	JOSE FICIO Data Signal	П		
PHONEOUTN	Phone Negative Output	A		
PHONEOUTP	•			
PHONEIUN	Phone Positive Output Phone Negative Input	A		
FHUNCININ	rnone negative input	Α		



Pin/Signal	Description	Туре
PHONEINP	Phone Positive Input	Α
MICINN[2:1]	MIC Negative Input	Α
MICINP[2:1]	MIC Positive Input	Α
LINEINR	Line-in Right Input	A
LINEINL	Line-in Left Input	Α
HBIAS	HBIAS	A
MBIAS	MBIAS	Α
VRA1	Reference (1.5V)	A
VRA2	Reference (1.5V)	Α
AVCC	Analog Power Supply	Р
VRP	Reference (3.0V)	Α
AGND	Analog Ground	G
HPOUTR	Headphone Right Channel Output	A
HPOUTL	Headphone Left Channel Output	A
HPVCCIN	Headphone VCC Input	Α
HPVCCBP	Headphone VCC Bypass	A
HPCOM	Headphone Common Reference	Α
HPCOMFB	Headphone Common Reference Feedback	A
HPBP	Headphone Bypass Output	A
AIF-SYNC	Audio Codec SYNC Signal	A
AIF-BCLK	Audio Codec Clock Signal	A
AIF-DOUT	Audio Codec Data Output	A
AIF-DIN	Audio Codec Data Input	A
LRADC	, and could be a second	
LRADC0	LRADC Input	A
SPI		
SPI0-CS	SPI Chip Select Signal	I/O
SPI0-CLK	SPI Clock Signal	I/O
SPI0-MOSI	SPI Master Data Out, Slave Data In	I/O
SPI0-MISO	SPI Master Data In, Slave Data Out	I/O
UART (x=[3:0])	of Financial Bata III, Glave Bata Gut	li C
UARTX-TX	UART Data Transmit	0
UARTX-RX	UART Data Receive	
UARTX-RTS	UART Data Request to Send	0
UARTX-CTS	UART Data Clear to Send	I
TWI (x=[2:0])(Open-Drain)	OAIXT Data Cical to Octio	1
TWIx-SCK	TWI Clock Signal	I/O
TWIX-SOR TWIX-SDA	TWI Data Signal	I/O
SD/MMC (x=[2:0])	TWI Data Sigilal	1/0
SDCx-D	SD/MMC/SDIO Data Bit	I/O
SDCx-CLK	SD/MMC/SDIO Clock	0
SDCx-CMD	SD/MMC/SDIO Clock SD/MMC/SDIO Command Signal	I/O
SDC-RST	SD/MMC/SDIO Command Signal SD/MMC/SDIO Reset Signal	0
	SD/MINIC/SDIO Reset Signal	U
PCM(x=[1:0])	DCM SYNC	1/0
PCMx-SYNC	PCM SYNC	1/0
PCMx-CLK	PCM Clock	1/0
PCMx-DOUT	PCM Data Output	0
PCMx-DIN	PCM Data Input	
RSB	Don of A	
S-RSB-SCK	RSB Clock	0
S-RSB-SDA	RSB Data	I/O



Pin/Signal	Description	Type
POWER		· •
VDD-CPU	CPU Power Supply	P
VDD-CPUS	CPUS Power Supply	Р
VDD-SYS	System Power Supply	Р
VCC-EFUSE	EFUSE Power Supply	р
GND	Ground	G
VCC-IO	IO Power Supply	P





5

ELECTRICAL CHARACTERISTICS

5.1. ABSOLUTE MAXIMUM RATINGS

Functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

SYMBOL	PARAMETER	MIN	MAX	UNIT
T _{STG}	Storage Temperature	-40	125	°C
Ivo	In/Out current for input and output	-40	40	mA
V_{ESD}	ESD stress voltage	-4000	+4000	V _{ESD}
VCC-IO	DC Supply Voltage for I/O	-0.3	3.6	V
VDD-DLL	Power Supply for DLL	-0.3	2.75	V
VCC-DRAM	Power Supply for DRAM	-0.3	1.65	V
VCC-PLL	Power Supply for PLL	-0.3	3.6	V
VCC-RTC	Power Supply for RTC	-0.3	3.6	V
AVCC	DC Supply Voltage for Analog Part	-0.3	3.6	V
VCC-USB	Power Supply for USB PHY	-0.3	3.6	V
VCC-DSI	Power Supply for DSI	-0.3	3.6	V
VDD-CPU	Power Supply for CPU	-0.3	1.5	V
VDD-SYS	Power Supply for System	-0.3	1.5	V

5.2. RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT
T _a	Ambient Operating Temperature[Commercial]	-20	-	75	°C
	Operating Temperature[Extended]	-	-	-	°C
VCC-IO	DC Supply Voltage for I/O	1.7	1.8~3.3	3.6	V



SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT
VDD-DLL	Power Supply for DLL	2.35	2.5	2.65	V
VCC-DRAM	Power Supply for DRAM (DDR3L)	1.283	1.35	1.575	V
	Power Supply for DRAM (DDR3)	1.425	1.5	1.575	V
VCC-PLL	Power Supply for PLL	2.7	3.0	3.3	V
VCC-USB	Power Supply for USB PHY	3.0	3.3	3.45	V
VCC-RTC	Power Supply for RTC	2.7	3.0	3.3	V
AVCC	DC Supply Voltage for Analog Part	2.7	3.0	3.3	V
VCC-DSI	Power Supply for MIPI DSI	2.7	3.3	3.6	V
VDD-CPU	Power Supply for CPU	0.9	1.1	1.4	V
VDD-SYS	Power Supply for System	0.9	1.1	1.4	V

5.3. DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{IH}	High-Level Input Voltage	VCC-IO=3.0V	0.7 x VCC-IO	-	VCC-IO + 0.3	V
V _{IL}	Low-Level Input Voltage	VCC-IO=3.0V	-0.3	-	0.3 x VCC-IO	V
R _{PU}	Input pull-up resistance	VCC-IO=3.0V	50	100	150	K
R _{PD}	Input pull-down resistance	VCC-IO=3.0V	50	100	150	K
V_{HYS}	Hysteresis Voltage		0.1 x VCC-IO	-	-	V
I _{IH}	High-Level Input Current	VCC-IO=3.0V, VI=3.0V	-10	-	10	uA
I _{IL}	Low-Level Input Current	VCC-IO=3.0V, VI=0V	-10	-	10	uA
V _{OH}	High-Level Output Voltage	VCC-IO=3.0V	VCC-IO - 0.2	-	-	V
V_{OL}	Low-Level Output Voltage	VCC-IO=3.0V	-	-	0.2	V
l _{oz}	Tri-State Output Leakage Current	VCC-IO=3.0V	-10	-	10	uA
C _{IN}	Input Capacitance	-	-	-	5	pF
C_{OUT}	Output Capacitance	-	-	-	5	pF

5.4. OSCILLATOR ELECTRICAL CHARACTERISTICS

The R16 contains two oscillators: a 24MHz oscillator and a 32768Hz oscillator. Each oscillator requires a specific crystal.

The R16 device operation requires following two input clocks:

- The 32768Hz frequency is used for low frequency operation.
- The 24MHz frequency is used to generate the main source clock of the Y10 device.



5.4.1. 24MHz OSCILLATOR CHARACTERISTICS

The 24MHz crystal is connected between the HOSCI (amplifier input) and HOSCO (amplifier output).

SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT
1/(tCPMAIN)	Crystal Oscillator Frequency Range	-	24	-	MHz
t _{ST}	Startup Time	-	-	-	ms
	Frequency Tolerance at 25°C	-50	-	50	ppm
	Oscillation Mode	Fundamental	-		
	Maximum Change Over Temperature Range	-50	-	50	ppm
PON	Drive Level	-	-	50	uW
CL	Equivalent Load Capacitance	-	-	-	pF
CL1,CL2	Internal Load Capacitance(CL1=CL2)	-	-	-	pF
RS	Series Resistance(ESR)	-	-		Ω
	Duty Cycle	30	50	70	%
CM	Motional Capacitance	-	-	1.0	pF
C _{SHUT}	Shunt Capacitance	-			pF
R _{BIAS}	Internal Bias Resistor	-		-	МΩ

5.4.2. 32768HZ OSCILLATOR CHARACTERISTICS

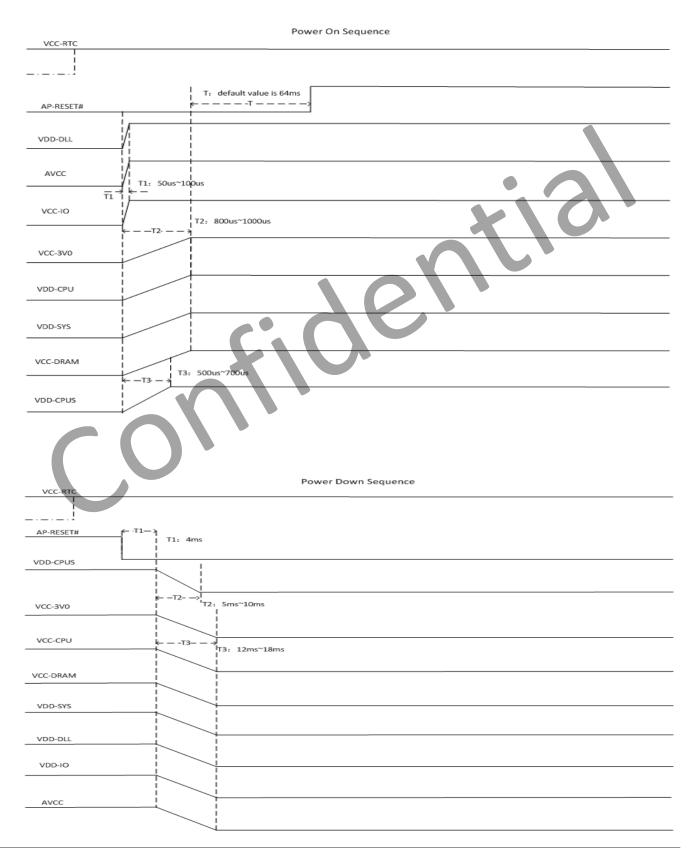
The 32768Hz crystal is connected between the LOSCI (amplifier input) and LOSCO (amplifier output).

SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT
1/(tCPMAIN)	Crystal Oscillator Frequency Range	-	32768	-	Hz
t _{ST}	Startup Time	-	-	-	ms
	Frequency Tolerance at 25°C	-50	-	50	ppm
	Oscillation Mode	Fundament	-		
	Maximum Change Over Temperature Range	-50	-	50	ppm
PON	Drive Level	-	-	50	uW
CL	Equivalent Load Capacitance	-	-	-	pF
CL1,CL2	Internal Load Capacitance(CL1=CL2)	-	-	-	pF
RS	Series Resistance(ESR)	-	-	- ms 50 ppm 50 ppm 50 uW - pF - pF - Ω 70 % - pF - pF	
	Duty Cycle	30	50	70	%
СМ	Motional Capacitance	-	-	-	pF
C _{SHUT}	Shunt Capacitance	-	-	-	pF
R _{BIAS}	Internal Bias Resistor	-	-	-	МΩ



5.5. POWER UP/DOWN SEQUENCE

The external voltage regulator and other power-on devices must provide the processor with a specific sequence of power and resets to ensure proper operations.



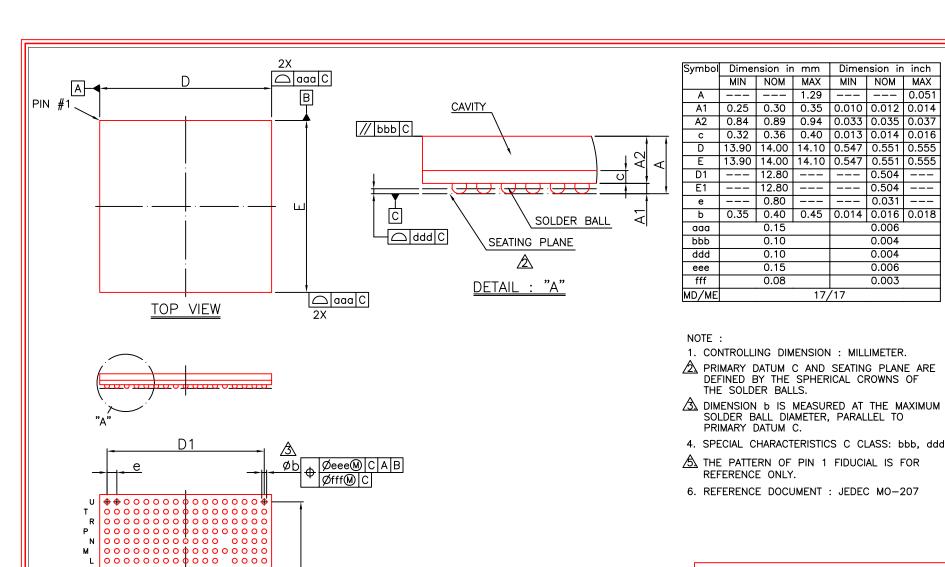


6

PIN ASSIGNMENT

6.1. PIN MAP

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	
A	DA6	PE12	PE10	PE8	PE6	PE4	PC16	PC14	PC12	PC10	PC8	PC7	PG4	PG2	PG0	PG9	PG6	А
В	DA8	PE13	PE11	PE9	PE7	PE5	PC15	PC13	PC11	PC9	PC4		PG5	PG3	PG1	PG8	PG7	В
С	DA14	DA11	PE14	PE16	PEO	PE2	PF5	PF3	PF1	PC5	PC2	PC1	PH5	PG13	PG12	PG11	PG10	С
D	DA1	DA4	PE15	PE17	PE1	PE3	PF4	PF2	PF0	PC6	PC3	PCO	PH4	PH3	PH2	PH1	РНО	D
E	DA12	DA10	DA15	DAO	VDD-CPU	VDD-CPU	VDD-CPU	VDD-SYS	VDD-SYS	VDD-SYS	VCC-IO	VCC-IO		РН9	PH8	PH7	PH6	E
F	DA5	DA2	DA13	DA9	VDD-CPU	VDD-CPU	VDD-CPU	GND	GND	GND	VCC-IO	VCC-IO	~	PB6	РВ7	PB3	PB2	F
G	DCK	DCKB	DRST	DA7	VDD-CPU	VDD-CPU	GND	GND	GND	GND	GND	VCC-IO		PB4	PB5	PB1	PB0	G
н	DQ6	DQ7	DA3	DBA2	VCC-DRAM	VCC-DRAM	GND	GND	GND	GND	GND	GND	AGND	нрсом	LINEINL	HPCOMFB	HPVCCBP	н
J	DQ4	DQ5	DBAO	DCKE	VCC-DRAM	VCC-DRAM	GND	GND	GND	GND	GND	GND		HBIAS	LINEINR	HPOUTR	HPOUTL	J
K	DQSOB	DQ\$0	DWE	DBA1	VCC-DRAM	VDD-SYS	GND	GND	GND	GND	GND	GND	HPVCCIN	MBIAS	PHONEINN	VRA1	VRA2	К
L	DQ2	DQ3	DODT	DRAS	VCC-DRAM	VDD-SYS	DODT1	GND	GND	GND	GND	VCC-USB		LRADCO	PHONEINP	AVCC	VRP	L
M	DQ0	DQ1	DCAS	DVREF	VCC-PLL	VDD-SYS	VDD-SYS	VCC-EFUSE	GND	GND	VCC-PD	VCC-RTC	RTCVIO	VDD-CPUS	PHONEOUT	MIC1N	MIC1P	М
N	DQ15	DQM0	DCS	GND	DCS1	VCC-DSI	DCKE1	VDD-SYS	VDD-SYS	VDD-SYS	VCC-PD	VCC-HSIC		NMI	PHONEOUT	MIC2N	MIC2P	N
P	DQ13	DQ14	VDD-DLL	DSI-DOP	DSI-D1P	DSI-D3P	PD15	PD13	PD11	PD7	PD5	PD3	PL9	PL5	PL1	PLO	RESET	Р
R	DQ\$1	DQ12	DZQ	DSI-DON	DSI-D1N	DSI-D3N	PD14	PD12	PD10	PD6	PD4	PD2	PL8	PL4	X32KFOUT	X32KOUT	X32KIN	R
Т	DQ\$1B	DQ11	DQM1	X24MOUT	DSI-CKP	DSI-D2P	PD27	PD25	PD23	PD21	PD19	PL11	PL7	PL3	HSIC-STR	USB-DM0	USB-DP0	т
U	DQ9	DQ10	DQ8	X24MIN	DSI-CKN	DSI-D2N	PD26	PD24	PD22	PD20	PD18	PL10	PL6	PL2	HSIC-DAT	USB-DM1	USB-DP1	U
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	1



TITLE: 282LD TFBGA (14X14 mm) PACKAGE OUTLINE APPR. PE. DWG NO. (M/D,B/P,S/P,S/G) PD. REV NO. DATE QM. CHK. DWG.

NOM

0.551

0.504

0.504

0.031

0.006

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0.004

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0.003

MAX

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BOTTOM VIEW





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Allwinner Technology Co., Ltd.
4th Floor, B6 Building, NO.1, Software Road,
Zhuhai, Guangdong Province, China

Contact Us: service@allwinnertech.com

www.allwinnertech.com